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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10056350	FILING DATE 01/24/2002	CLASS 257	SUBCLASS 669	GAU 2825	EXAMINER V. YEVSIKOV
**APPLICANTS: Cobbley Chad;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A DIV OF 09/060,740 04/15/1998 ABN YES VY USP 6,504,57					
** FOREIGN APPLICATIONS VERIFIED: NO VY					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no V. YEVSIKOV VY		ATTORNEY DOCKET NO 11675.143.2	
TITLE : Process for providing electrical connection between a semiconductor die and a semiconductor die receiving member					
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for 0.6
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drawg.	Fig. Drawg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner	
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